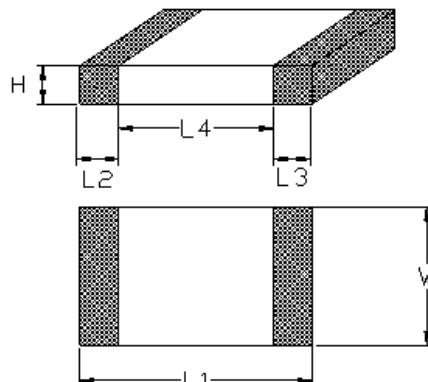


Multilayer Ceramic Chip Capacitor

Part Number : 1210Y0500474KXTM01	Description : 1210 50V 470nF ±10% X7R (2R1)	
Syfer Technology Ltd offers Multilayer Ceramic Chip Capacitors of the highest quality and reliability for a range of demanding applications. Manufactured using our "Wet Process", the range encompasses 10V to 12kV capability, with a variety of termination options including FlexiCap™, the worlds first commercially available flexible termination.		
Mechanical Specification		
Syfer Size Code	1210	
Length (L1) mm	3.2 ± 0.3	
Width (W) mm	2.5 ± 0.3	
Thickness (H) mm	2.0 Max.	
Termination Bands (L2,L3) mm	0.25 - 0.75	
Minimum Band Gap (L4) mm	1.4	
Termination Material	100% Matte Sn over Ni, FlexiCap™ base	
Solderability	IEC 60068-2-58	
RoHS Compliant to 2011/65/EC	Yes	
REACH Compliant	Yes	
Packaging	Taped and Reeled, 7 inch Reel	
General Electric Specifications		
Rated Voltage	50V	
Nominal Capacitance Value	470nF	
Capacitance Tolerance	±10%	
Tangent of Loss Angle (Tan δ)	≤0.025	
Capacitance and Tan δ Test Conditions	1Vrms @ 1kHz	
Voltage Proof (Voltage applied for 5 secs max. @ 50mA max. charge current)	2.5 x Rated Voltage	
Min Insulation Resistance (IR)	2.13 GΩ	
Dielectric Classification	X7R (2R1)	
Rated Temperature Range	-55°C - +125°C	
Maximum Capacitance Change over Temperature Range	No DC Voltage	±15%
	Rated DC Voltage	-
Climatic Category (IEC)	55/125/56	
Ageing Characteristic	Less than 2% per time decade	
Knowles (UK) Ltd., Old Stoke Road, Arminghall, Norwich, NR14 8SQ Tel: +44 1603 723300 Email: syfersales@knowles.com Web: http://www.syfer.com	<small>©</small> This datasheet is for a standard item and is confirmed valid on the date generated, the latest published data for this part may differ and is available at http://www.syfer.com or by contacting us at syfersales@knowles.com The information contained on this drawing is confidential and may not be copied in whole or part in any form or disclosed to a third party without the consent of Syfer Technology Ltd. and any customer mentioned within this specification.	
	Date: 19 April 2016	